Stellaris® LM4F120 LaunchPad Evaluation Board

User Manual



Literature Number: SPMU289C August 2012—Revised September 2013



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EK-LM4F120 Bill of Materials



Revision History www.ti.com

Revision History

This revision history highlights the changes made to the SPMU289B user's manual to make it an SPMU289C revision.

| SEE | ADDITIONS/MODIFICATIONS/DELETIONS | | | | |
|---|--|--|--|--|--|
| Section 2.1.4 Headers and BoosterPacks | Table 2-3, J1 Connector: • Updated/Changed first column header cell from "J4 Pin" to "J1 Pin" | | | | |

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.



Board Overview

The Stellaris® LM4F120 LaunchPad Evaluation Board (EK-LM4F120XL) is a low-cost evaluation platform for ARM® Cortex™-M4F-based microcontrollers. The Stellaris LaunchPad design highlights the LM4F120H5QR microcontroller USB 2.0 device interface and hibernation module. The Stellaris LaunchPad also features programmable user buttons and an RGB LED for custom applications. The stackable headers of the Stellaris LM4F120 LaunchPad BoosterPack XL interface demonstrate how easy it is to expand the functionality of the Stellaris LaunchPad when interfacing to other peripherals with Stellaris BoosterPacks and MSP430^{TMTM} BoosterPacks. Figure 1-1 shows a photo of the Stellaris LaunchPad.

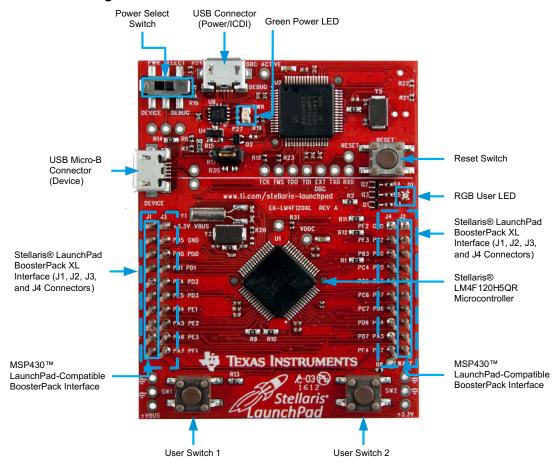


Figure 1-1. Stellaris LM4F120 LaunchPad Evaluation Board

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Kit Contents www.ti.com

1.1 Kit Contents

The Stellaris LM4F120 LaunchPad Evaluation Kit contains the following items:

- Stellaris LaunchPad Evaluation Board (EK-LM4F120XL)
- On-board Stellaris In-Circuit Debug Interface (ICDI)
- USB micro-B plug to USB-A plug cable
- README First document

1.2 Using the Stellaris LaunchPad

The recommended steps for using the Stellaris LM4F120 LaunchPad Evaluation Kit are:

- 1. **Follow the README First document included in the kit.** The README First document will help you get the Stellaris LaunchPad up and running in minutes. See the <u>Stellaris LaunchPad web page</u> for additional information to help you get started.
- 2. **Experiment with LaunchPad BoosterPacks.** A selection of Stellaris BoosterPacks and compatible MSP430 BoosterPacks can be found at the Stellaris LaunchPad web page.
- 3. Take your first step toward developing an application with Project 0 using your preferred ARM tool-chain and the Stellaris Peripheral Driver Library. Software applications are loaded using the on-board Stellaris In-Circuit Debug Interface (ICDI). See Chapter 3, Software Development, for the programming procedure. The StellarisWare Peripheral Driver Library Software Reference Manual contains specific information on software structure and function. For more information on Project 0, go to the Stellaris LaunchPad wiki page.
- 4. **Customize and integrate the hardware to suit an end application.** This user's manual is an important reference for understanding circuit operation and completing hardware modification.

You can also view and download almost six hours of training material on configuring and using the LaunchPad. Visit the Stellaris LaunchPad Workshop for more information and tutorials.

1.3 Features

Your Stellaris LaunchPad includes the following features:

- Stellaris LM4F120H5QR microcontroller
- USB micro-B connector for USB device
- RGB user LED
- Two user switches (application/wake)
- Available I/O brought out to headers on a 0.1-in (2.54-mm) grid
- On-board Stellaris ICDI
- Switch-selectable power sources:
 - ICDI
 - USB device
- Reset switch
- Preloaded RGB quickstart application
- Supported by StellarisWare software including the USB library and the peripheral driver library
- Stellaris LM4F120 LaunchPad BoosterPack XL Interface, which features stackable headers to expand the capabilities of the Stellaris LaunchPad development platform
 - For a complete list of available BoosterPacks that can be used with the Stellaris LaunchPad, see the Stellaris LaunchPad web page.



www.ti.com BoosterPacks

1.4 BoosterPacks

The Stellaris LaunchPad provides an easy and inexpensive way to develop applications with the Stellaris LM4F120H5QR microcontroller. Stellaris BoosterPacks and MSP430 BoosterPacks expand the available peripherals and potential applications of the Stellaris LaunchPad. BoosterPacks can be used with the Stellaris LaunchPad or you can simply use the on-board LM4F120H5QR microcontroller as its processor. See Chapter 2 for more information.

Build your own BoosterPack and take advantage of <u>Texas Instruments' website</u> to help promote it! From sharing a new idea or project, to designing, manufacturing, and selling your own BoosterPack kit, TI offers a variety of avenues for you to reach potential customers with your solutions.

1.5 Specifications

Table 1-1 summarizes the specifications for the Stellaris LaunchPad.

Table 1-1. EK-LM4F120XL Specifications

| Parameter | Value | | | | |
|------------------------|---|--|--|--|--|
| | 4.75 V_{DC} to 5.25 V_{DC} from one of the following sources: | | | | |
| Board supply voltage | Debugger (ICDI) USB Micro-B cable (connected to a PC) | | | | |
| | USB Device Micro-B cable (connected to a PC) | | | | |
| Dimensions | 2.0 in x 2.25 in x 0.425 in (5.0 cm x 5.715 cm x 10.795 mm) (L x W x H) | | | | |
| | • 3.3 V _{DC} (300 mA max) | | | | |
| Break-out power output | 5.0 V_{DC} (depends on 3.3 V_{DC} usage, 23 mA to 323 mA) | | | | |
| RoHS status | Compliant | | | | |



Hardware Description

The Stellaris LaunchPad includes a Stellaris LM4F120H5QR microcontroller and an integrated Stellaris ICDI as well as a range of useful peripheral features (as the block diagram in Figure 2-1 shows). This chapter describes how these peripherals operate and interface to the microcontroller.

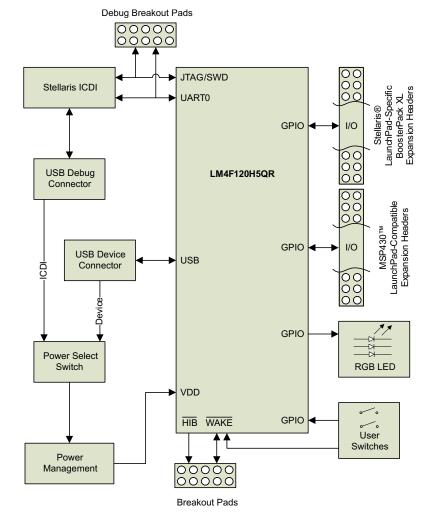


Figure 2-1. Stellaris LaunchPad Evaluation Board Block Diagram

2.1 Functional Description

2.1.1 Microcontroller

The Stellaris LM4F120H5QR is a 32-bit ARM Cortex-M4F-based microcontroller with 256-KB Flash memory, 32-KB SRAM, 80-MHz operation, USB device, Hibernation module, and a wide range of other peripherals. See the <u>LM4F120H5QR microcontroller data sheet</u> (literature number <u>SPMS294</u>) for complete device details.



Functional Description www.ti.com

Most of the microcontroller signals are routed to 0.1-in (2.54-mm) pitch headers. An internal multiplexer allows different peripheral functions to be assigned to each of these GPIO pads. When adding external circuitry, consider the additional load on the evaluation board power rails.

The LM4F120H5QR microcontroller is factory-programmed with a quickstart demo program. The quickstart program resides in on-chip Flash memory and runs each time power is applied, unless the quickstart application has been replaced with a user program.

2.1.2 USB Device

The Stellaris LaunchPad includes a USB micro-B connector to allow for USB 2.0 device operation. The signals shown in Table 2-1 are used for USB device.

| GPIO Pin | Pin Function | USB Device |
|----------|--------------|------------|
| PD4 | USB0DM | D- |
| PD5 | USB0DP | D+ |

Table 2-1. USB Device Signals

When connected as a USB device, the evaluation board can be powered from either the Stellaris ICDI or the USB Device connectors. The user can select the power source by moving the POWER SELECT switch (SW3) to the Device position. See the *Power Management* schematic (appended to this document).

2.1.3 User Switches and RGB User LED

The Stellaris LaunchPad comes with an RGB LED. This LED is used in the preloaded RGB quickstart application and can be configured for use in custom applications.

Two user buttons are included on the board. The user buttons are both used in the preloaded quickstart application to adjust the light spectrum of the RGB LED as well as go into and out of hibernation. The user buttons can be used for other purposes in the user's custom application.

The evaluation board also has a green power LED. Table 2-2 shows how these features are connected to the pins on the microcontroller.

| GPIO Pin | Pin Function | USB Device | | |
|----------|--------------|-----------------|--|--|
| PF4 | GPIO | SW1 | | |
| PF0 | GPIO | SW2 | | |
| PF1 | GPIO | RGB LED (Red) | | |
| PF2 | GPIO | RGB LED (Blue) | | |
| PF3 | GPIO | RGD LED (Green) | | |

Table 2-2. User Switches and RGB LED Signals

2.1.4 Headers and BoosterPacks

The two double rows of stackable headers are mapped to most of the GPIO pins of the LM4F120H5QR microcontroller. These rows are labeled as connectors J1, J2, J3, and J4. Connectors J3 and J4 are located 0.1 in (2.54 mm) inside of the J1 and J2 connectors. All 40 header pins of the J1, J2, J3, and J4 connectors make up the Stellaris LM4F120 LaunchPad BoosterPack XL Interface. Table 2-3 through Table 2-6 show how these header pins are connected to the microcontroller pins and which GPIO functions can be selected.

NOTE: To configure the device peripherals easily and intuitively using a graphical user interface (GUI), see the Stellaris LM4F Pinmux Utility found at www.ti.com/tool/lm4f pinmux. This easy-to-use interface makes setting up alternate functions for GPIOs simple and error-free.



Functional Description www.ti.com

Table 2-3. J1 Connector⁽¹⁾

| J1 Pin | GPIO | Stellaris Pin | GPIOPCTL Register Setting | | | | | | | |
|---------|------|------------------|---------------------------|------|---------|---------|--------|--------|---|----|
| JI FIII | GFIO | | GPIOAMSEL | 1 | 2 | 3 | 7 | 8 | 9 | 14 |
| 1.01 | | | | | 3.3 | 3 V | | | | |
| 1.02 | PB5 | 57 | AIN11 | - | SSI2Fss | - | T1CCP1 | CAN0Tx | - | - |
| 1.03 | PB0 | 45 | _ | U1Rx | - | - | T2CCP0 | - | - | - |
| 1.04 | PB1 | 46 | - | U1Tx | - | - | T2CCP1 | - | - | - |
| 1.05 | PE4 | 59 | AIN9 | U5Rx | - | I2C2SCL | - | CAN0Rx | - | - |
| 1.06 | PE5 | 60 | AIN8 | U5Tx | - | I2C2SDA | - | CAN0Tx | - | - |
| 1.07 | PB4 | 58 | AIN10 | - | SSI2CIk | - | T1CCP0 | CAN0Rx | - | - |
| 1.08 | PA5 | 22 | - | - | SSI0Tx | - | - | - | - | - |
| 1.09 | PA6 | 23 | - | - | - | I2C1SCL | - | _ | _ | - |
| 1.10 | PA7 | 24 | - | - | _ | I2C1SDA | - | _ | _ | 1 |

Shaded cells indicate configuration for compatibility with the MSP430 LaunchPad.

Table 2-4. J2 Connector⁽¹⁾

| J2 Pin | GPIO | Stellaris | GPIOPCTL Register Setting | | | | | | | |
|---------------------|------|-----------|---------------------------|-------|---------|---------|--------|-----|-----|----|
| | GPIO | Pin | GPIOAMSEL | 1 | 2 | 3 | 7 | 8 | 9 | 14 |
| 2.01 | | | | | G1 | ND | | | | |
| 2.02 | PB2 | 47 | - | - | - | I2C0SCL | T3CCP0 | - | - | - |
| 2.03 | PE0 | 9 | AIN3 | U7Rx | - | - | - | - | - | _ |
| 2.04 | PF0 | 28 | - | U1RTS | SSI1Rx | CAN0Rx | T0CCP0 | NMI | C0o | _ |
| 2.05 | | | | | RES | SET | | | | |
| 2.06 ⁽²⁾ | PB7 | 4 | - | - | SSI2Tx | - | T0CCP1 | - | - | _ |
| 2.07 ⁽³⁾ | PB6 | 1 | - | - | SSI2Rx | - | T0CCP0 | - | - | - |
| 2.08 | PA4 | 21 | - | - | SSI0Rx | - | - | - | - | - |
| 2.09 | PA3 | 20 | - | - | SSI0Fss | - | - | - | - | _ |
| 2.10 | PA2 | 19 | _ | _ | SSI0Clk | - | - | _ | - | _ |

Shaded cells indicate configuration for compatibility with the MSP430 LaunchPad.

J2.06 (PB7) is also connected via a $0-\Omega$ resistor to J3.04 (PD1).

J2.07 (PB6) is also connected via a $0-\Omega$ resistor to J3.03 (PD0).



www.ti.com Functional Description

Table 2-5. J3 Connector⁽¹⁾

| J3 Pin | GPIO | Stellaris | | | GF | IOPCTL Regi | ister Setting | | | |
|---------------------|------|-----------|-----------|---------|---------|-------------|---------------|---|-----|------|
| | GPIO | Pin | GPIOAMSEL | 1 | 2 | 3 | 7 | 8 | 9 | 14 |
| 3.01 | | | | | 5.0 | V | | | | |
| 3.02 | | | | | GI | ND | | | | |
| 3.03 | PD0 | 61 | AIN7 | SSI3CIk | SSI1Clk | I2C3SCL | WT2CCP0 | - | - | _ |
| 3.04 | PD1 | 62 | AIN6 | SSI3Fss | SSI1Fss | I2C3SDA | WT2CCP1 | - | - | - |
| 3.05 | PD2 | 63 | AIN5 | SSI3Rx | SSI1Rx | - | WT3CCP0 | - | - | - |
| 3.06 | PD3 | 64 | AIN4 | SSI3Tx | SSI1Tx | - | WT3CCP1 | - | - | _ |
| 3.07 | PE1 | 8 | AIN2 | U7Tx | - | - | - | - | - | - |
| 3.08 | PE2 | 7 | AIN1 | - | - | - | - | - | - | _ |
| 3.09 | PE3 | 6 | AIN0 | - | - | - | - | - | - | - |
| 3.10 ⁽²⁾ | PF1 | 29 | _ | U1CTS | SSI1Tx | - | T0CCP1 | - | C1o | TRD1 |

⁽¹⁾ Shaded cells indicate configuration for compatibility with the MSP430 LaunchPad.

Table 2-6. J4 Connector

| J4 Pin | GPIO | CDIO | Stellaris | | | GI | PIOPCTL Reg | ister Setting | | | |
|---------------------|------|------|-----------|------|---------|---------|-------------|---------------|---|-------|--|
| J4 FIII | GFIO | Pin | GPIOAMSEL | 1 | 2 | 3 | 7 | 8 | 9 | 14 | |
| 4.01 ⁽¹⁾ | PF2 | 30 | - | | SSI1Clk | | T1CCP0 | | | TRD0 | |
| 4.02 ⁽¹⁾ | PF3 | 31 | - | | SSI1Fs | CAN0Tx | T1CCP1 | | | TRCLK | |
| 4.03 | PB3 | 48 | - | | | I2C0SDA | T3CCP1 | | | | |
| 4.04 | PC4 | 16 | C1- | U4Rx | U1Rx | | WT0CCP0 | U1RTS | | | |
| 4.05 | PC5 | 15 | C1+ | U4Tx | U1Tx | | WT0CCP1 | U1CTS | | | |
| 4.06 | PC6 | 14 | C0+ | U3Rx | | | WT1CCP0 | | | | |
| 4.07 | PC7 | 13 | C0- | U3Tx | | | WT1CCP1 | | | | |
| 4.08 | PD6 | 53 | - | U2Rx | | | WT5CCP0 | | | | |
| 4.09 ⁽¹⁾ | PD7 | 10 | - | U2Tx | | | WT5CCP1 | NMI | | | |
| 4.10 ⁽¹⁾ | PF4 | 5 | _ | | | | T2CCP0 | | | | |

 $^{^{(1)}}$ Not recommended for BoosterPack use. This signal tied to on-board function via a $0-\Omega$ resistor.

Connectors J1 and J2 of the Stellaris LM4F120 LaunchPad BoosterPack XL Interface provide compatibility with MSP430 LaunchPad BoosterPacks. Highlighted functions (shaded cells) in Table 2-3 through Table 2-5 indicate configuration for compatibility with the MSP430 LaunchPad.

A complete list of Stellaris BoosterPacks and Stellaris LaunchPad-compatible MSP430 BoosterPacks is available at www.ti.com/stellaris-launchpad.

Not recommended for BoosterPack use. This signal tied to on-board function via a $0-\Omega$ resistor.



Power Management www.ti.com

2.2 Power Management

2.2.1 Power Supplies

The Stellaris LaunchPad can be powered from one of two power sources:

- On-board Stellaris ICDI USB cable (Debug, Default)
- USB device cable (Device)

The POWER SELECT switch (SW3) is used to select one of the two power sources. Select only one source at a time.

2.2.2 Hibernate

The Stellaris LaunchPad provides an external 32.768-kHz crystal (Y1) as the clock source for the LM4F120H5QR Hibernation module clock source. The current draw while in Hibernate mode can be measured by making some minor adjustments to the Stellaris LaunchPad. This procedure is explained in more detail later in this section.

The conditions that can generate a wake signal to the Hibernate module on the Stellaris LaunchPad are waking on a Real-time Clock (RTC) match and/or waking on assertion of the \overline{WAKE} pin. (1) The second user switch (SW2) is connected to the \overline{WAKE} pin on the microcontroller. The \overline{WAKE} pin, as well as the V_{DD} and \overline{HIB} pins, are easily accessible through breakout pads on the Stellaris LaunchPad. See the appended schematics for details.

There is no external battery source on the Stellaris LaunchPad Hibernation module, which means the VDD3ON power control mechanism should be used. This mechanism uses internal switches to remove power from the Cortex-M4F processor as well as to most analog and digital functions while retaining I/O pin power.

To measure the Hibernation mode current or the Run mode current, the VDD jumper that connects the 3.3 V pin and the MCU_PWR pin must be removed. See the complete **schematics** (appended to this document) for details on these pins and component locations. An ammeter should then be placed between the 3.3 V pin and the MCU_PWR pin to measure I_{DD} (or I_{HIB_VDD3ON}). The LM4F120H5QR microcontroller uses V_{DD} as its power source during V_{DD3ON} Hibernation mode, so I_{DD} is the Hibernation mode (VDD3ON mode) current. This measurement can also be taken during Run mode, which measures I_{DD} the microcontroller running current.

2.2.3 Clocking

The Stellaris LaunchPad uses a 16.0-MHz crystal (Y2) to complete the LM4F120H5QR microcontroller main internal clock circuit. An internal PLL, configured in software, multiples this clock to higher frequencies for core and peripheral timing.

The Hibernation module is clocked from an external 32.768-KHz crystal (Y1).

2.2.4 Reset

The RESET signal into the LM4F120H5QR microcontroller connects to the RESET switch and to the Stellaris ICDI circuit for a debugger-controlled reset.

External reset is asserted (active low) under any of three conditions:

- Power-on reset (filtered by an R-C network)
- · RESET switch held down
- By the Stellaris ICDI circuit when instructed by the debugger (this capability is optional, and may not be supported by all debuggers)

⁽¹⁾ If the board does not turn on when you connect it to a power source, the microcontroller might be in Hibernate mode (depending on the programmed application). You must satisfy one of the programmed wake conditions and connect the power to bring the microcontroller out of Hibernate mode and turn on the board.



2.3 Stellaris In-Circuit Debug Interface (ICDI)

The Stellaris LaunchPad evaluation board comes with an on-board Stellaris In-Circuit Debug Interface (ICDI). The Stellaris ICDI allows for the programming and debug of the LM4F120H5QR using the LM Flash Programmer and/or any of the supported tool chains. Note that the Stellaris ICDI supports only JTAG debugging. An external debug interface can be connected for Serial Wire Debug (SWD) and SWO (trace).

Table 2-7 shows the pins used for JTAG and SWD. These signals are also mapped out to easily accessible breakout pads and headers on the board.

Table 2-7. Stellaris In-Circuit Debug Interface (ICDI) Signals

| GPIO Pin | Pin Function |
|----------|--------------|
| PC0 | TCK/SWCLK |
| PC1 | TMS/SWDIO |
| PC2 | TDI |
| PC3 | TDO/SWO |

2.3.1 Virtual COM Port

When plugged in to a PC, the device enumerates as a debugger and a virtual COM port. Table 2-8 shows the connections for the COM port to the pins on the microcontroller.

Table 2-8. Virtual COM Port Signals

| GPIO Pin | Pin Function |
|----------|--------------|
| PA0 | U0RX |
| PA1 | U0TX |



Software Development

This chapter provides general information on software development as well as instructions for Flash memory programming.

3.1 Software Description

The StellarisWare software provided with the Stellaris LaunchPad provides access to all of the peripheral devices supplied in the design. The Stellaris Peripheral Driver Library is used to operate the on-chip peripherals as part of StellarisWare.

StellarisWare includes a set of example applications that use the StellarisWare Peripheral Driver Library. These applications demonstrate the capabilities of the LM4F120H5QR microcontroller, as well as provide a starting point for the development of the final application for use on the Stellaris LaunchPad evaluation board.

3.2 Source Code

The complete source code including the source code installation instructions are provided at www.ti.com/stellaris-launchpad. The source code and binary files are installed in the DriverLib tree.

3.3 Tool Options

The source code installation includes directories containing projects and/or makefiles for the following toolchains:

- Keil ARM RealView® Microcontroller Development System
- · IAR Embedded Workbench for ARM
- Sourcery CodeBench
- Texas Instruments' Code Composer Studio™ IDE

Download evaluation versions of these tools from www.ti.com/stellaris. Due to code size restrictions, the evaluation tools may not build all example programs. A full license is necessary to re-build or debug all examples.

Instructions on installing and using each of the evaluation tools can be found in the Quickstart guides (for example, Quickstart-Keil, Quickstart-IAR) which are available for download from the evaluation kit section of the TI website at www.ti.com/stellaris.

For detailed information on using the tools, see the documentation included in the tool chain installation or visit the respective web site of the tool supplier.



3.4 Programming the Stellaris LaunchPad Evaluation Board

The Stellaris LaunchPad software package includes pre-built binaries for each of the example applications. If you have installed StellarisWare to the default installation path of *C:\StellarisWare*, you can find the example applications in *C:\StellarisWare\boards\ek-Im4f120xI*. The on-board Stellaris ICDI is used with the Stellaris LM Flash Programmer tool to program applications on the Stellaris LaunchPad.

Follow these steps to program example applications into the Stellaris LaunchPad evaluation board using the Stellaris ICDI:

- 1. Install LM Flash Programmer on a PC running Microsoft® Windows®.
- 2. Switch the **POWER SELECT** switch to the right for Debug mode.
- Connect the USB-A cable plug to an available port on the PC and the Micro-B plug to the Debug USB port on the board.
- 4. Verify that the POWER LED D4 on the board is lit.
- 5. Run the LM Flash Programmer.
- 6. In the Configuration tab, use the Quick Set control to select the EK-LM4F120XL evaluation board.
- 7. Move to the Program tab and click the **Browse** button. Navigate to the example applications directory (the default location is *C:\StellarisWare\boards\ek-Im4f120xI*).
- 8. Each example application has its own directory. Navigate to the example directory that you want to load and then into the directory which contains the binary (*.bin) files. Select the binary file and click **Open**.
- Set the *Erase Method* to *Erase Necessary Pages*, check the Verify After Program box, and check Reset MCU After Program.

Program execution starts once the Verify process is complete.



References, PCB Layout, and Bill of Materials

4.1 References

In addition to this document, the following references are available for download at www.ti.com/stellaris:

- Stellaris LM4F120H5QR Microcontroller Data Sheet (literature number SPMS294).
- StellarisWare Driver Library. Available for download at www.ti.com/tool/sw-drl.
- StellarisWare Driver Library User's Manual, publication SW-DRL-UG (literature number SPMU019).
- TPS73633 Low-Dropout Regulator with Reverse Current Protection Data Sheet (literature number SBVS038)
- TLV803 Voltage Supervisor Data Sheet (literature number SBVS157)
- Texas Instruments' Code Composer Studio IDE website: www.ti.com/ccs

Additional support:

- RealView MDK (www.keil.com/arm/rvmdkkit.asp)
- IAR Embedded Workbench (www.iar.com).
- Sourcery CodeBench development tools (www.codesourcery.com/gnu_toolchains/arm).

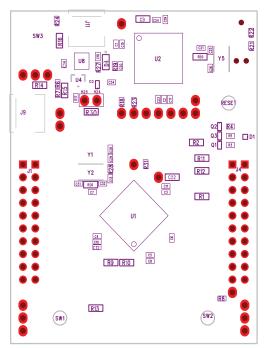


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4.2 Component Locations

Plots of the top-side component locations are shown in Figure 4-1 and the board dimensions are shown in Figure 4-2.

Figure 4-1. Stellaris LaunchPad Component Locations (Top View)





Bill of Materials (BOM) www.ti.com

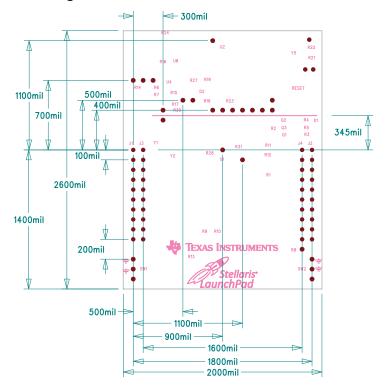


Figure 4-2. Stellaris LaunchPad Dimensions

NOTE: Units are in mils (one thousandth of an inch): 1 mil = 0.001 inch (0.0254 mm).

4.3 Bill of Materials (BOM)

Table 4-1 shows the bill of materials for the EK-LM4F120XL evaluation board.

Table 4-1. EK-LM4F120 Bill of Materials

| Item | Ref Des | Qty | Description | Manufacturer | Manufacturer Part No |
|------|-------------------------------------|-----|---|-----------------------------|------------------------|
| 1 | C1-2, C7, C12, C14 | 5 | Capacitor, 0402, X5R, 10 V, Low ESR | Johanson Dielectrics Inc | 100R07X105KV4T |
| 2 | C25-26, C31-32 | 4 | Capacitor, 10 pF, 50 V, 5%, NPO/COG, 0402 | Murata | GRM1555C1H100JZ01D |
| 3 | C28-29 | 2 | Capacitor, 24 pF, 50 V, 5%, NPO/COG, 0402 | TDK | C1005C0G1H240J |
| 4 | C3, C5, C8, C15, C18-19, C21 | 7 | Capacitor, 0.01 µF 25 V, 10% 0402 X7R | Taiyo Yuden | TMK105B7103KV-F |
| 5 | C4, C6, C10-11, C17, C20, C23-24 | 8 | Capacitor, 0.1 μF 16 V, 10% 0402 X7R | Taiyo Yuden | EMK105B7104KV-F |
| 6 | C9, C22 | 2 | Capacitor, 2.2 μF, 16 V, 10%, 0603, X5R | Murata | GRM188R61C225KE15D |
| 7 | D1 | 1 | LED, Tri-Color RGB, 0404 SMD Common Anode | Everlight | 18-038/RSGHBHC1-S02/2T |
| 8 | D2 | 1 | Diode, Dual Schottky, SC70, BAS70 Common Cathode | Diodes Inc | BAS70W-05-7-F |
| 9 | D4 | 1 | LED, Green 565 nm, Clear 0805 SMD | Lite-On | LTST-C171GKT |
| 10 | H24 | 1 | Header, 1x2, 0.100, T-Hole, | 3M | 961102-6404-AR |
| | | | Vertical Unshrouded, 0.220 Mate | FCI | 68001-102HLF |
| 11 | H25 | 1 | Jumper, 0.100, Gold, Black, Closed | Sullins | SPC02SYAN |



www.ti.com Bill of Materials (BOM)

Table 4-1. EK-LM4F120 Bill of Materials (continued)

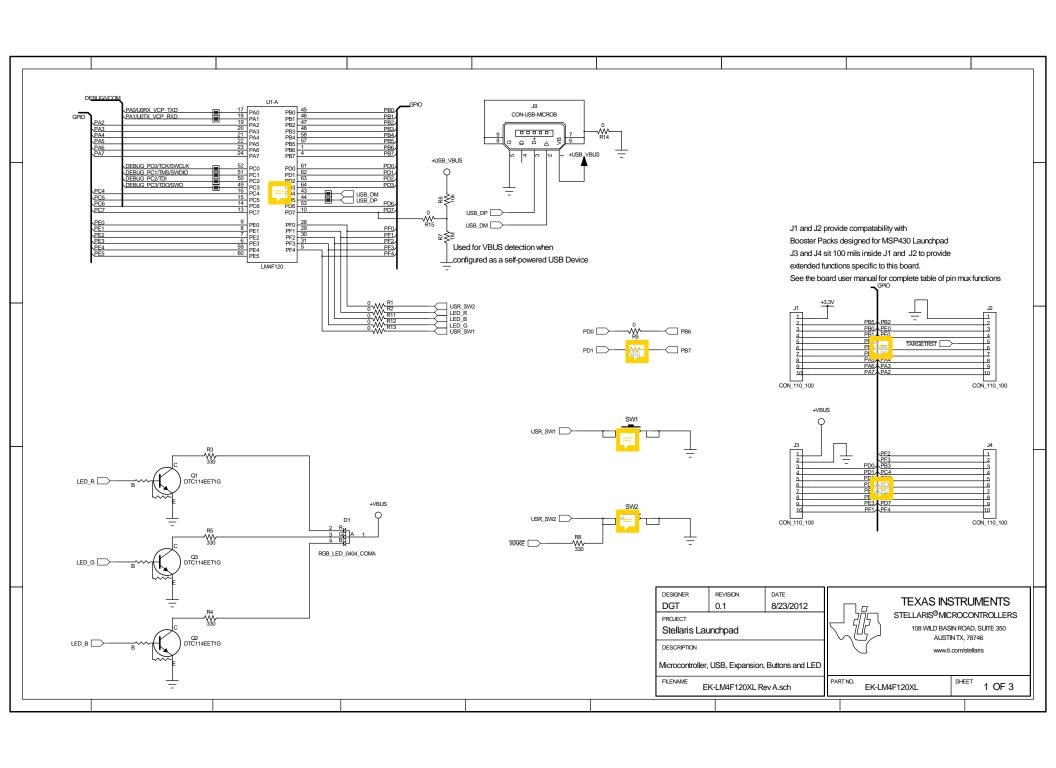
| Item | Ref Des | Qty | Description | Manufacturer | Manufacturer Part No |
|------|----------------------------|-----|---|-------------------|------------------------|
| 12 | J1, J4 | 2 | Header, 2x10, T-Hole Vertical unshrouded stacking | Samtec | SSW-110-23-S-D |
| 13 | J9, J11 | 2 | USB Connectors Micro B Recept RA SMT BTTM MNT | Hirose | ZX62-B-5PA |
| 14 | Q1-3 | 3 | NPN SC70 pre-biased | Diodes Inc | DTC114EET1G |
| 15 | R1-2, R9-16, R20, R26 | 12 | Resistor, 0 Ω 1/10W 0603 SMD | Panasonic | ERJ-3GEY0R00V |
| 16 | R3-5, R8, R27 | 5 | Resistor, 330 Ω, 1/10W, 5%, 0402 | Yageo | RC0402FR-07330RL |
| 17 | R,6 R17-19, R21-23, R28 | 8 | Resistor, 10 k Ω , 1/10W, 5%, 0402 Thick Film | Yageo | RC0402FR-0710KL |
| 18 | R7, R31 | 2 | Resistor, 1 MΩ 1/10W, 5%, 0402 | RΩ | MCR01MRTF1004 |
| 19 | RESET SW1, SW2 | 3 | Switch, Tact 6 mm SMT, 160gf | Omron | B3S-1000 |
| 20 | SW3 | 1 | Switch, DPDT, SMT 300 mA × 2 at 6 V | C K Components | JS202011SCQN |
| 21 | U1, U2 | 2 | Stellaris MCU LM4F120H5QRFIGA3 | Texas Instruments | LM4F120H5QRFIG |
| 22 | U4 | 1 | IC, Single Voltage Supervisor, 5 V, DBV | Texas Instruments | TLV803MDBZR |
| 23 | U8 | 1 | Regulator, 3.3 V, 400 mA, LDO | Texas Instruments | TPS73633DRBT |
| 24 | Y1 | 1 | Crystal, 32.768 kHz Radial Can | Abracon | AB26TRB-32.768KHZ- T |
| 25 | Y2, Y5 | 2 | Crystal, 16.00 MHz 5.0x3.2mm SMT | NDK | NX5032GA-16.000000 MHz |
| | | | | Abracon | ABM3-16.000 MHz-B2- T |
| | | | PCB Do Not Populate List (Shown for information only) | | |
| 26 | C13, C34 | 2 | Capacitor, 0.1 µF 16 V, 10% 0402 X7R | Taiyo Yuden | EMK105B7104KV-F |
| 27 | R24 | 1 | Resistor, 330 Ω, 1/10W, 5%, 0402 | Yageo | RC0402FR-07330RL |
| 28 | R30 | 1 | Resistor, 0 Ω 1/10W 0603 SMD | Panasonic | ERJ-3GEY0R00V |
| | | | <u> </u> | 1 | |

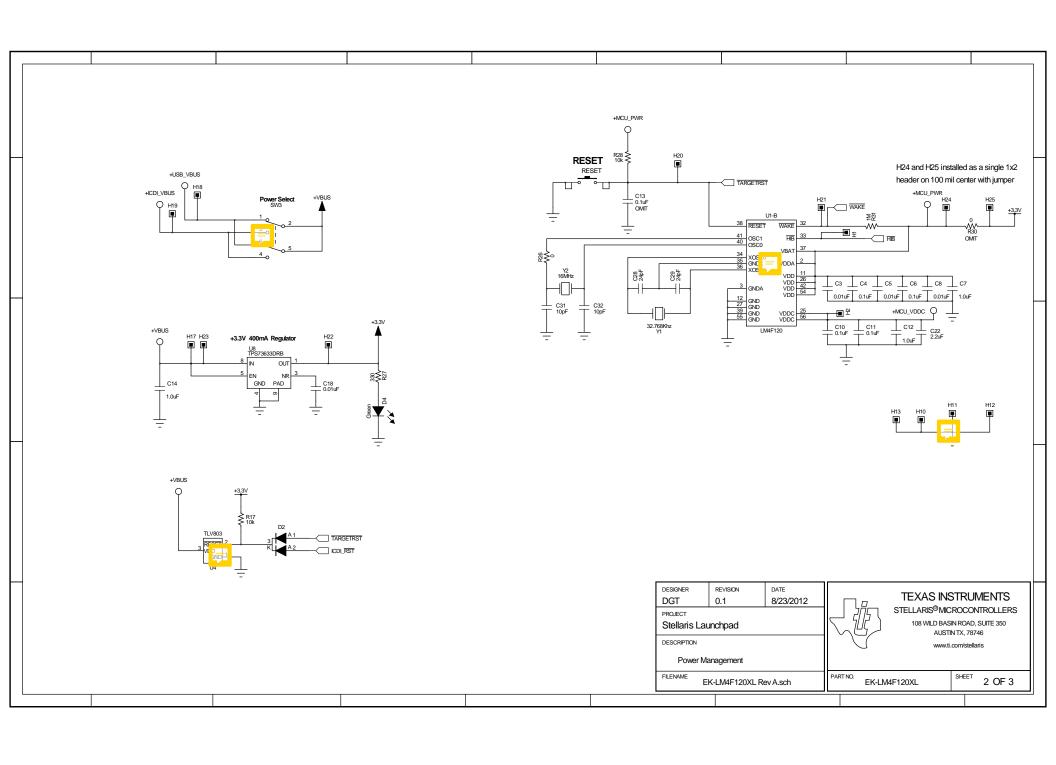


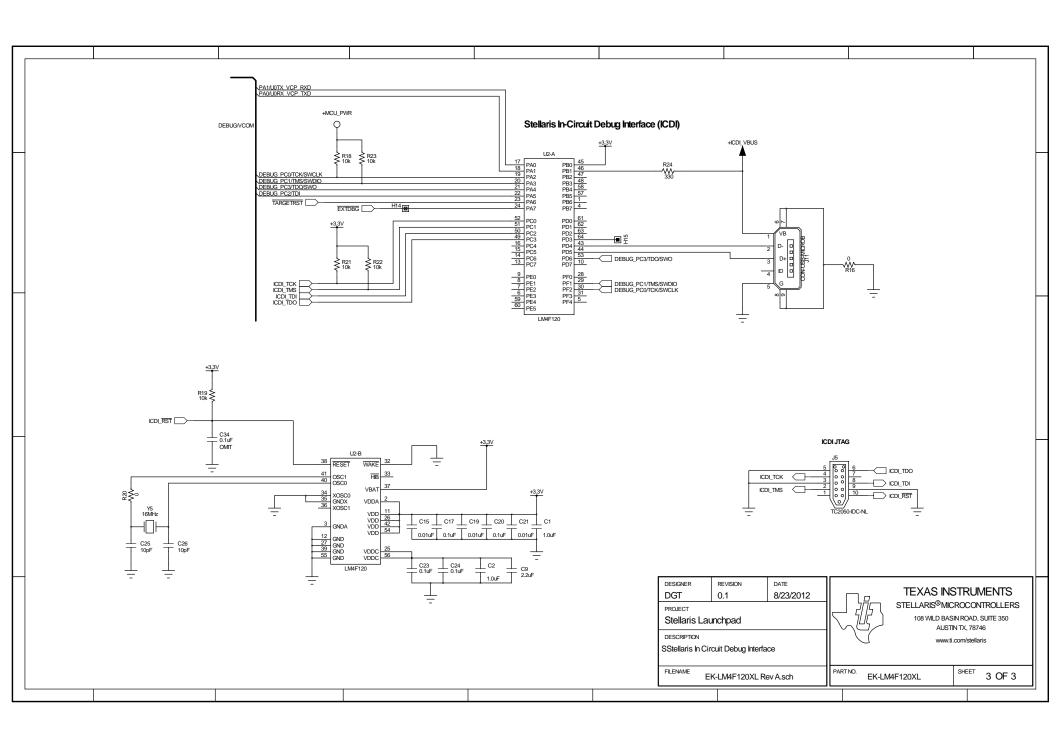
Schematics

This section contains the complete schematics for the Stellaris LaunchPad board.

- Microcontroller, USB, Expansion, Buttons, and LED
- Power Management
- Stellaris In-Circuit Debug Interface







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As noted in the EVM User's Guide and/or EVM itself, this EVM and/or accompanying hardware may or may not be subject to the Federal Communications Commission (FCC) and Industry Canada (IC) rules.

For EVMs **not** subject to the above rules, this evaluation board/kit/module is intended for use for ENGINEERING DEVELOPMENT, DEMONSTRATION OR EVALUATION PURPOSES ONLY and is not considered by TI to be a finished end product fit for general consumer use. It generates, uses, and can radiate radio frequency energy and has not been tested for compliance with the limits of computing devices pursuant to part 15 of FCC or ICES-003 rules, which are designed to provide reasonable protection against radio frequency interference. Operation of the equipment may cause interference with radio communications, in which case the user at his own expense will be required to take whatever measures may be required to correct this interference.

General Statement for EVMs including a radio

User Power/Frequency Use Obligations: This radio is intended for development/professional use only in legally allocated frequency and power limits. Any use of radio frequencies and/or power availability of this EVM and its development application(s) must comply with local laws governing radio spectrum allocation and power limits for this evaluation module. It is the user's sole responsibility to only operate this radio in legally acceptable frequency space and within legally mandated power limitations. Any exceptions to this are strictly prohibited and unauthorized by Texas Instruments unless user has obtained appropriate experimental/development licenses from local regulatory authorities, which is responsibility of user including its acceptable authorization.

For EVMs annotated as FCC - FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant

Caution

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

FCC Interference Statement for Class A EVM devices

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

FCC Interference Statement for Class B EVM devices

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- · Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- · Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

For EVMs annotated as IC - INDUSTRY CANADA Compliant

This Class A or B digital apparatus complies with Canadian ICES-003.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

Concerning EVMs including radio transmitters

This device complies with Industry Canada licence-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concerning EVMs including detachable antennas

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication.

This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Cet appareil numérique de la classe A ou B est conforme à la norme NMB-003 du Canada.

Les changements ou les modifications pas expressément approuvés par la partie responsable de la conformité ont pu vider l'autorité de l'utilisateur pour actionner l'équipement.

Concernant les EVMs avec appareils radio

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes : (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante.

Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

[Important Notice for Users of EVMs for RF Products in Japan]

This development kit is NOT certified as Confirming to Technical Regulations of Radio Law of Japan

If you use this product in Japan, you are required by Radio Law of Japan to follow the instructions below with respect to this product:

- Use this product in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
- 2. Use this product only after you obtained the license of Test Radio Station as provided in Radio Law of Japan with respect to this product, or
- 3. Use of this product only after you obtained the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to this product. Also, please do not transfer this product, unless you give the same notice above to the transferee. Please note that if you could not follow the instructions above, you will be subject to penalties of Radio Law of Japan.

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Your Sole Responsibility and Risk. You acknowledge, represent and agree that:

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- 3. Since the EVM is not a completed product, it may not meet all applicable regulatory and safety compliance standards (such as UL, CSA, VDE, CE, RoHS and WEEE) which may normally be associated with similar items. You assume full responsibility to determine and/or assure compliance with any such standards and related certifications as may be applicable. You will employ reasonable safeguards to ensure that your use of the EVM will not result in any property damage, injury or death, even if the EVM should fail to perform as described or expected.
- 4. You will take care of proper disposal and recycling of the EVM's electronic components and packing materials.

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